IN THE CLAIMS

Please amend the claims as follows:

Claims 1-15 (Canceled).

Claim 16 (New): A bistable MEMS microswitch produced on a substrate and configured to electrically connect ends of at least two conductive tracks, including a beam suspended above a surface of the substrate, wherein the beam is embedded at its two ends and is subjected to compressive stress when the beam is in a non-deformed position, wherein the beam includes an electrical contact-forming mechanism configured to produce a lateral connection with ends of the two conductive tracks when the beam is deformed in a horizontal direction with respect to the surface of the substrate, the microswitch comprising:

means for actuating the beam so as to place the beam either in a first deformed position, corresponding to a first stable state, or in a second deformed position, corresponding to a second stable state and opposite the first deformed position with respect to the non-deformed position,

wherein the electrical contact-forming mechanism ensures connection of the ends of the two conductive tracks when the beam is in its deformed position.

Claim 17 (New): A microswitch according to claim 16, wherein the microswitch is a dual microswitch, and the first deformed position corresponds to connection of ends of two first conductive tracks, and the second deformed position corresponds to connection of ends of two second conductive tracks.

Claim 18 (New): A microswitch according to claim 16, wherein the microswitch is a single microswitch, and the first deformed position corresponds to connection of the ends of

two conductive tracks and the second deformed position corresponds to an absence of a connection.

Claim 19 (New): A microswitch according to claim 16, wherein the beam is made of a dielectric or semiconductor material and the electrical contact-forming mechanism includes an electrically conductive pad integrated into the beam.

Claim 20 (New): A microswitch according to claim 19, wherein the means for actuating the beam includes thermal actuators using a bimetal effect.

Claim 21 (New): A microswitch according to claim 20, wherein each thermal actuator includes a block of thermally conductive material in contact with an electrical resistance.

Claim 22 (New): A microswitch according to claim 19, wherein the means for actuating the beam includes means for implementing electrostatic forces.

Claim 23 (New): A microswitch according to claim 19, wherein the means for actuating the beam includes thermal actuators using a bimetal effect and means for implementing electrostatic forces.

Claim 24 (New): A microswitch according to claim 16, wherein the beam is made of an electrically-conductive material.

Claim 25 (New): A microswitch according to claim 24, wherein the means for actuating the beam includes means for implementing electrostatic forces.

Claim 26 (New): A microswitch according to claim 16, wherein the electrical contact-forming means mechanism is configured to be embedded between the ends of the conductive tracks to be connected.

Claim 27 (New): A microswitch according to claim 26, wherein the ends of the conductive tracks have a flexibility enabling them to match the form of the electrical contact-forming mechanism during a connection.

Claim 28 (New): A microswitch according to claim 16, further comprising release spring-forming means for at least one of the embedded ends of the beam.

Claim 29 (New): A microswitch according to claim 16, wherein the electrical contact-forming mechanism provides an ohmic contact.

Claim 30 (New): A microswitch according to claim 16, wherein the electrical contact-forming mechanism provides a capacitive contact.